MODEL NO : ET024QV01-K

MODEL VERSION: 01

SPEC VERSION : 1.0

ISSUED DATE: 2017-12-05

■**Preliminary Specification**

□**Final Product Specification**

Customer :_____

Approved by	Notes

Table of Contents

Record of Revision

Rev	Issued Date	Description	Editor
1.0	2017-12-05	Preliminary Specification Release	Xunqiang Ji

1 General Specifications

Feature		Spec
Display Spec.	Size	2.4 inch
	Resolution	240 x RGB x 320
	Technology Type	a-Si
	Pixel Configuration	RGB Vertical Stripe
	Pixel pitch(mm)	0.153 x 0.153
	Display Mode	Transf lective /Normally Black
	Viewing Direction	ALL
Mechanical Characteristics	LCM (W x H x D) (mm)	42.92X60.26X2.45
	Active Area(mm)	36.72(H) *48.96(V)
	With /Without TSP	Without TSP
	LED Numbers	4 LEDS
	Driver IC	ST7789V
	Weight (g)	TBD
Electrical Characteristics	Interface	RGB/MCU Interface
	Color Depth	262K

Note 1: Viewing direction for best image quality is different from TFT definition. There is a 180 degree shift.

Note 2: Requirements on Environmental Protection: Q/S0002

Note 3: LCM weight tolerance: ± 5%

2 Input/Output Terminals

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	VCI	Supply voltage(3.3V).	P
3	IOVCC	Supply voltage(1.65-3.3V).	P
4	IM2	MPU Parallel interface bus and serial interface select If use RGB Interface must select serial interface. Fix this pin at VCI and GND.	I
5	IM1		I
6	IM0		I
7	RESET	This signal will reset the device and must be applied to properly initialize the chip.	I
8	CS	Chip select input pin (“Low” enable). fix this pin at VCI or GND when not in use.	I
9	DC(SPI-SCL)	-Display data/command selection pin in parallel interface. -This pin is used to be serial interface clock. DC=’1’: display data or parameter. DC=’0’: command data. -If not used, please fix this pin at VDDI or DGND.	I
10	WR(SPI-RS)	-Write enable in MCU parallel interface. - Display data/command selection pin in 4-line serial interface. - Second Data lane in 2 data lane serial interface. -If not used, please fix this pin at VDDI or DGND.	I
11	RD	Serves as a read signal and MCU read data at the rising edge. fix this pin at VCI or GND when not in use.	I
12	VSYNC	Frame synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.	I
13	HSYNC	Line synchronizing signal for RGB interface operation. fix this pin at VCI or GND when not in use.	I
14	ENABLE	Data enable signal for RGB interface operation. fix this pin at VCI or GND when not in use.	I
15	DOTCLK	Dot clock signal for RGB interface operation. Fix this pin at VCI or GND when not in use.	I
16	SDA	Serial input signal. The data is latched on the rising edge of the SCL signal. fix this pin at VCI or GND when not in use.	I
17-34	DB0-DB17	18-bit parallel bi-directional data bus for MCU system and RGB i	I/0

		nterface mode . Fix to GND level when not in use	
35	SDO	SPI interface output pin. -The data is output on the falling edge of the SCL signal. -If not used, let this pin open.	O
36	LEDA	Anode pin of backlight	P
37	LEDK1	Cathode pin OF backlight	P
38	LEDK2	Cathode pin OF backlight	P
39	LEDK3	Cathode pin OF backlight	P
40	LEDK4	Cathode pin OF backlight	P
41	XR(NC)	Touch panel Right Glass Terminal	A/D
42	YU(NC)	Touch panel Bottom Film Terminal	A/D
43	XL(NC)	Touch panel LIFT Glass Terminal	A/D
44	YD(NC)	Touch panel Top Film Terminal	A/D
45	GND	Ground.	P

3 Absolute Maximum Ratings

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VCI	-0.3	4.6	**V**
Digital Interface Supply Voltage	IOVCC	-0.3	4.6	
Operating temperature	T_{OP}	-20	+70	℃
Storage temperature	T_{ST}	-30	+80	℃

4 Electrical Characteristics

4.1 Driving TFT LCD Panel

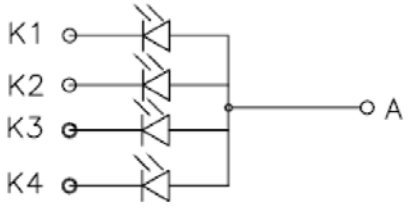
Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	VCI	2.4	2.75	3.3	V	
Digital Interface Supply Voltage	IOVCC	1.65	1.8	3.3		
Normal mode Current consumption	IDD	--	8	--	mA	
Level input voltage	V_{IH}	0.7VDDIO		VDDIO	V	
	V_{IL}	GND		0.3V_{DDIO}	V	
Level output voltage	V_{OH}	0.8VDDIO		VDDIO	V	
	V_{OL}	GND		0.2VDDIO	V	

4.2 Backlight Unit

The backlight system is an edge-lighting type with 4 LED. The characteristics of the LED are shown in the following tables.

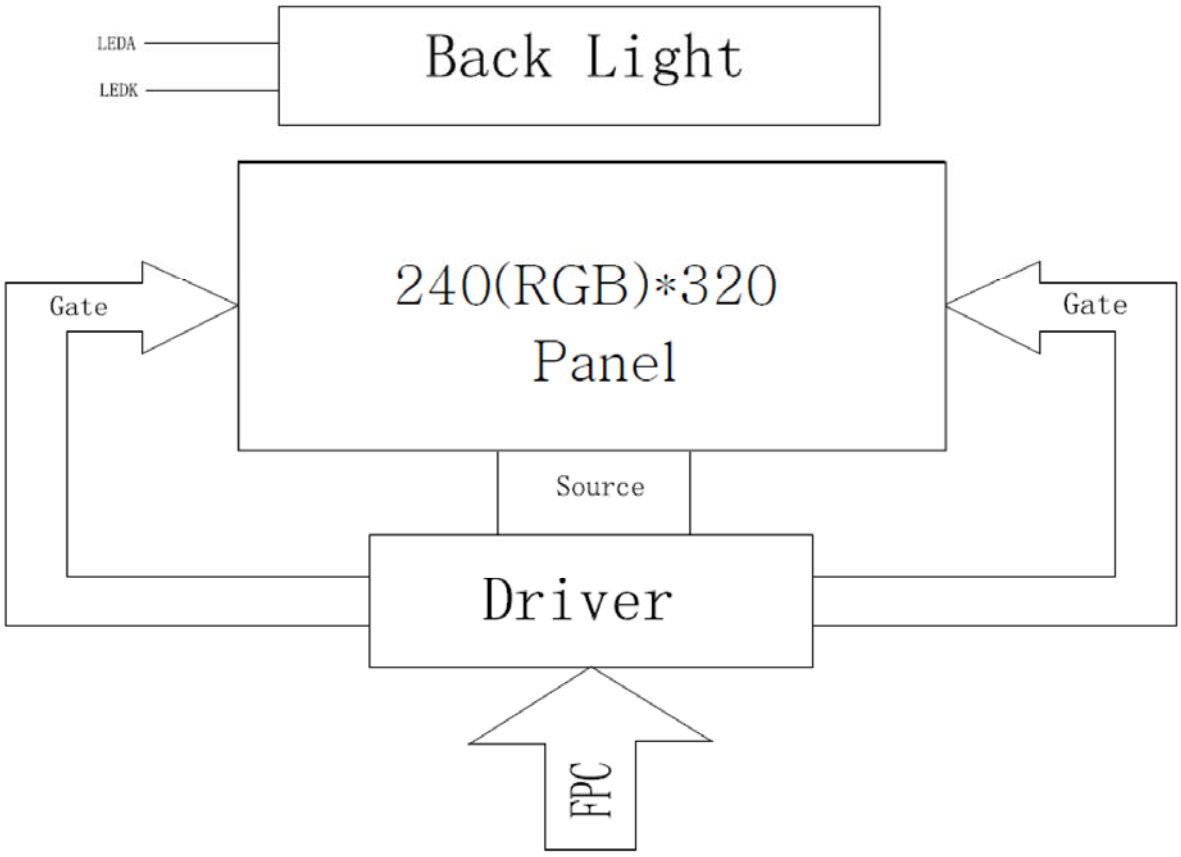
Item	Symbol	MIN	TYP	MAX	Unit	Remark
Backlight forward voltage	V_F	-	3.2	-	V	4 LEDs
Backlight forward current	I_F	-	80	-	mA	
LED life time	-	50000	-	-	Hrs	

Note 1: LED life time (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25±3 ℃, typical IL value indicated in the above table and the fL=50k Hz until the brightness becomes less than 50%.



4.3 Block Diagram

LCD Module diagram



5 Timing Chart

5.1 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus

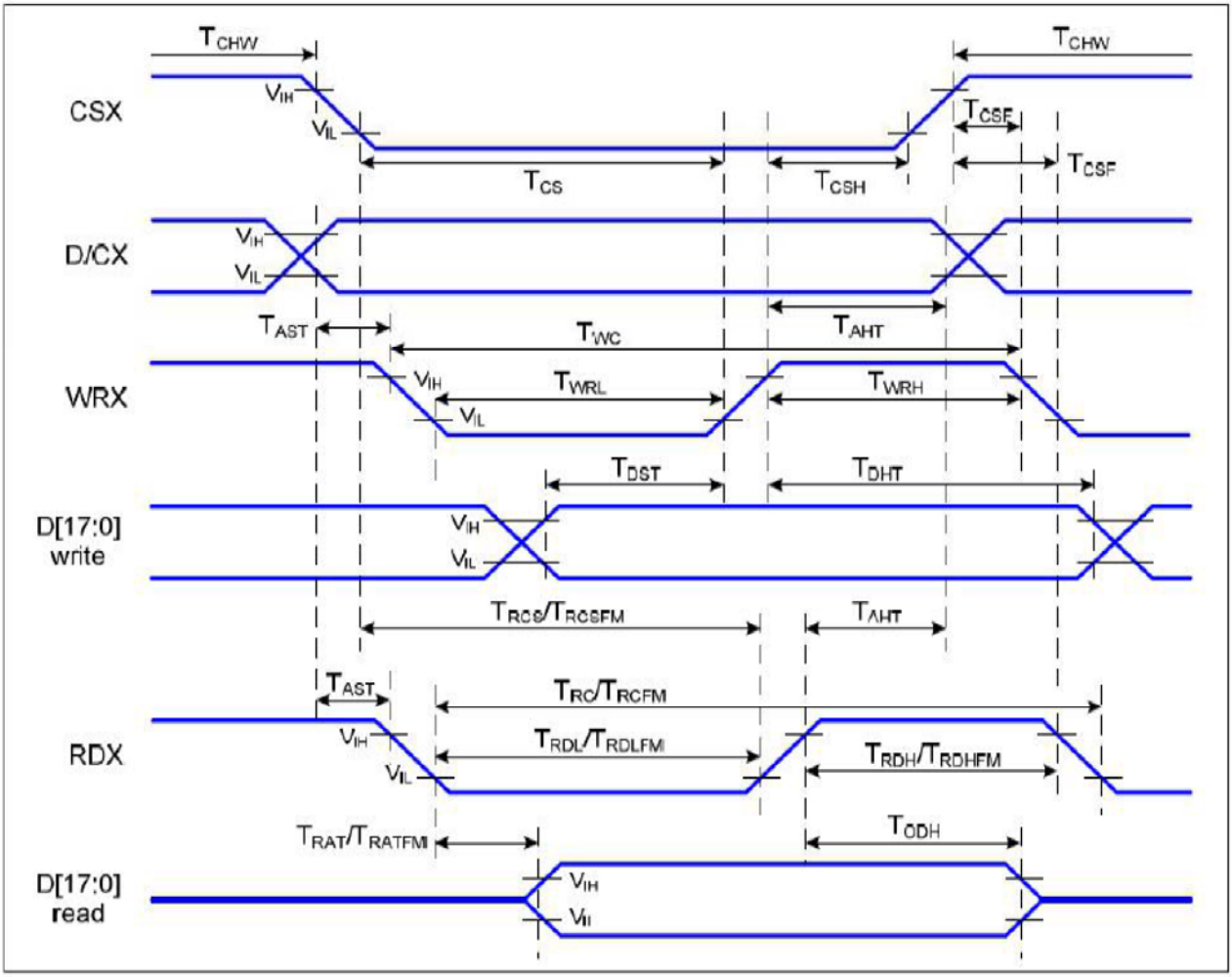


Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T_{AST}	Address setup time	0		ns	-
	T_{AHT}	Address hold time (Write/Read)	10		ns	
CSX	T_{CHW}	Chip select "H" pulse width	0		ns	-
	T_{CS}	Chip select setup time (Write)	15		ns	
	T_{RCS}	Chip select setup time (Read ID)	45		ns	
	T_{RCSFM}	Chip select setup time (Read FM)	355		ns	
	T_{CSF}	Chip select wait time (Write/Read)	10		ns	
	T_{CSH}	Chip select hold time	10		ns	
WRX	T_{WC}	Write cycle	66		ns	
	T_{WRH}	Control pulse "H" duration	15		ns	
	T_{WRL}	Control pulse "L" duration	15		ns	
RDX (ID)	T_{RC}	Read cycle (ID)	160		ns	When read ID data
	T_{RDH}	Control pulse "H" duration (ID)	90		ns	
	T_{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX (FM)	T_{RCFM}	Read cycle (FM)	450		ns	When read from frame memory
	T_{RDHFM}	Control pulse "H" duration (FM)	90		ns	
	T_{RDLFM}	Control pulse "L" duration (FM)	355		ns	
D[17:0]	T_{DST}	Data setup time	10		ns	For CL=30pF

	T_{DHT}	Data hold time	10		ns	
	T_{RAT}	Read access time (ID)		40	ns	
	T_{RATFM}	Read access time (FM)		340	ns	
	T_{ODH}	Output disable time	20	80	ns	

Table 4 8080 Parallel Interface Characteristics

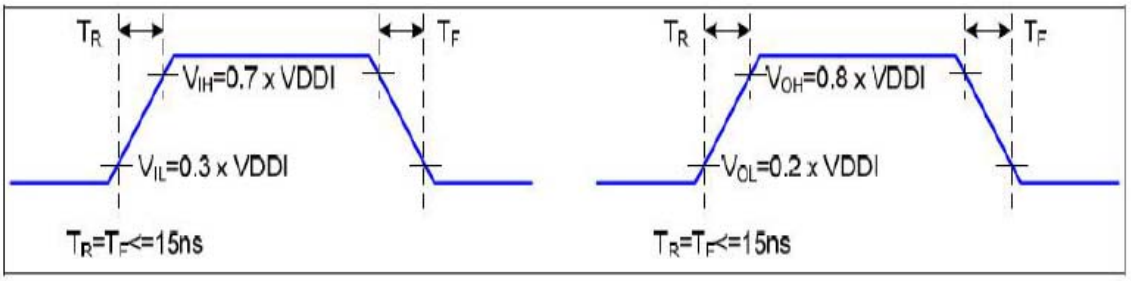


Figure 2 Rising and Falling Timing for I/O Signal

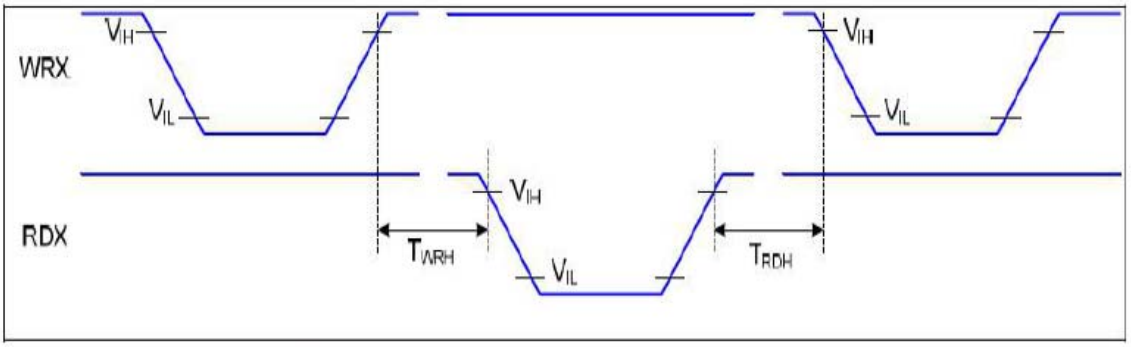


Figure 3 Write-to-Read and Read-to-Write Timing

Note: The rising time and falling time (Tr, Tf) of input signal and fall time are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

5.2 Serial Interface Characteristics (3-line serial)

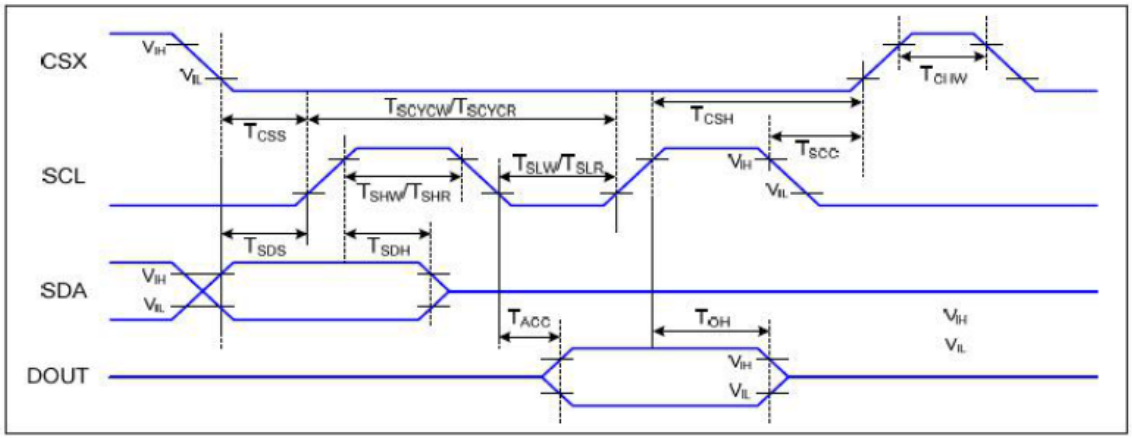


Figure 4 3-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

Table 5 3-line serial Interface Characteristics

Note : The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

5.3 Serial Interface Characteristics (4-line serial)

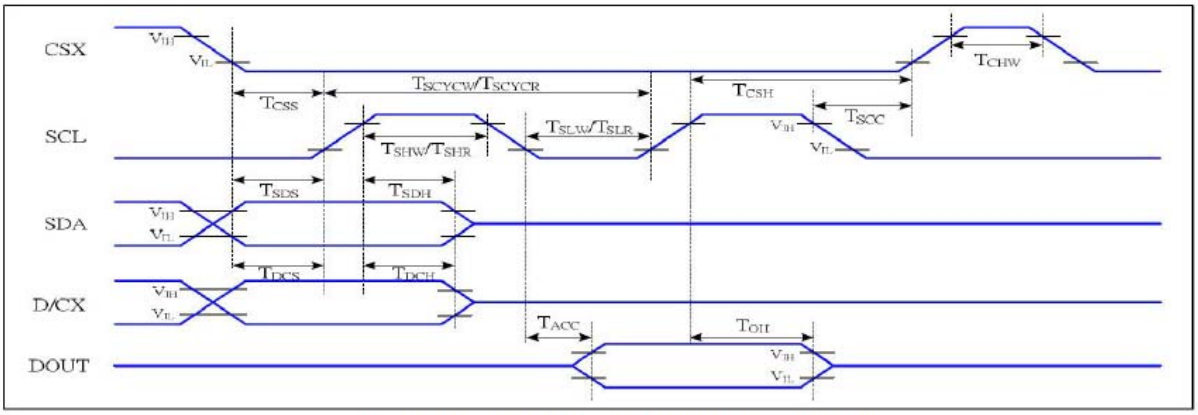


Figure 5 4-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	-write command & data ram
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	-read command & data ram
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
D/CX	T_{DCS}	D/CX setup time	10		ns	
	T_{DCH}	D/CX hold time	10		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

Table 6 4-line serial Interface Characteristics

Note : The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as

5.4 RGB Interface Characteristics

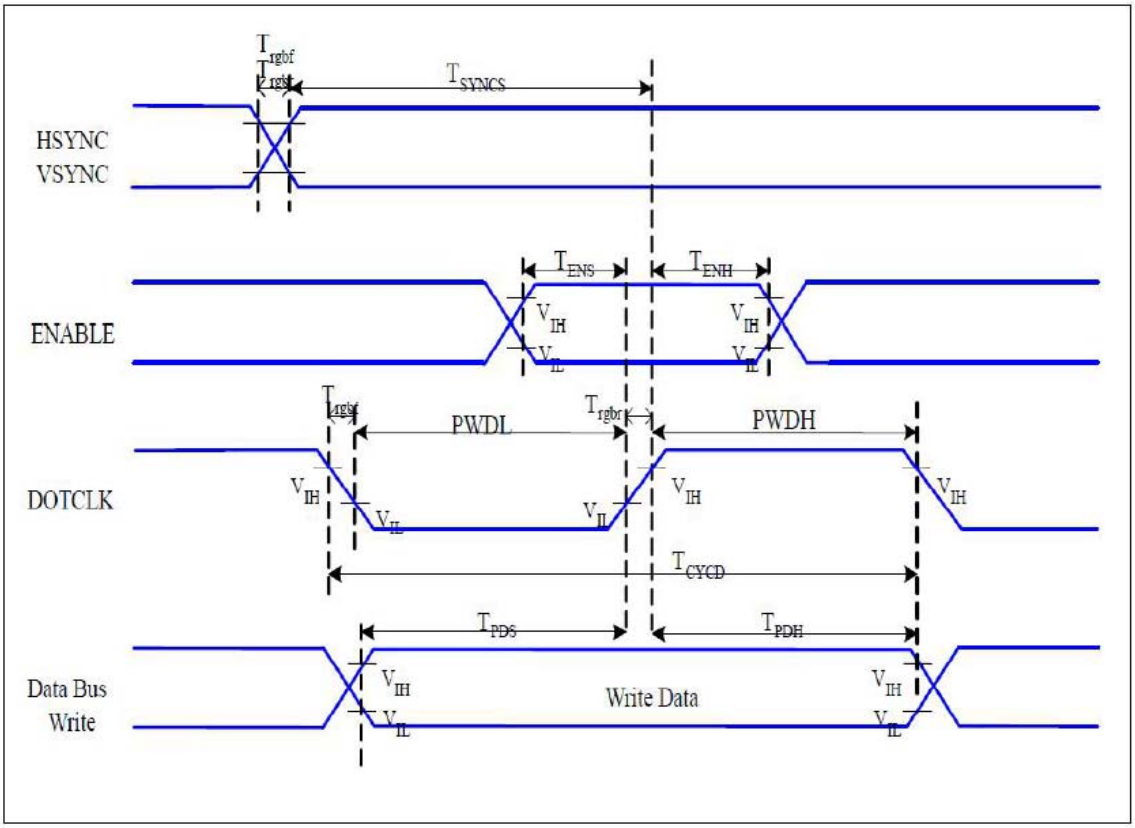


Figure 6 RGB Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	25	-	ns	
	T_{ENH}	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T_{PDS}	PD Data Setup Time	50	-	ns	
	T_{PDH}	PD Data Hold Time	50	-	ns	

Table 7 18/16 Bits RGB Interface Timing Characteristics

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	25	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	25	-	ns	

	T_{ENH}	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	25	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	25	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	55	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	10	ns	
DB	T_{PDS}	PD Data Setup Time	25	-	ns	
	T_{PDH}	PD Data Hold Time	25	-	ns	

Table 8 6 Bits RGB Interface Timing Characteristics

5.5 Reset Timing

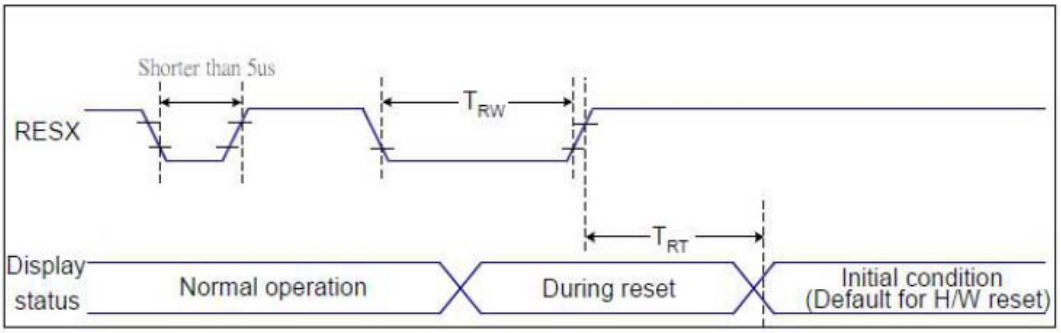


Figure 7 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Related Pins	Symbol	Parameter	MIN	MAX	Unit
RESX	TRW	Reset pulse duration	10	-	us
	TRT	Reset cancel	-	5 (Note 1, 5)	ms
				120 (Note 1, 6, 7)	ms

Table 9 Reset Timing

Notes:

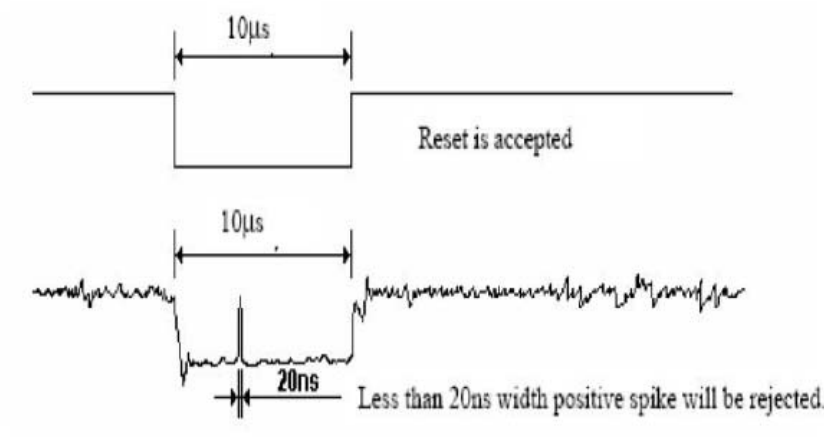
1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.

4. Spike Rejection also applies during a valid reset pulse as shown below:



5. When Reset applied during Sleep In Mode.

6. When Reset applied during Sleep Out Mode.

7. It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

6 Optical Characteristics

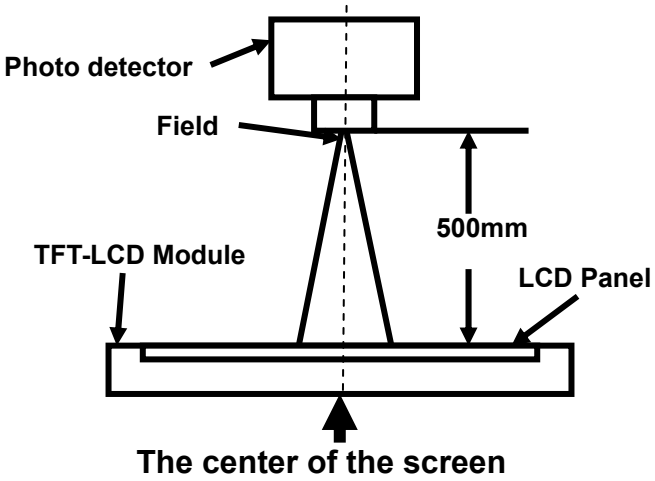
Item		Symbol	Condition	Min	Typ	Max	Unit	Remark
View Angles		θT	CR≧10	-	80	-	Degree	Note2,3
		θB		-	80	-		
		θL		-	80	-		
		θR		-	80	-		
Contrast Ratio		CR	θ=0°	-	600	-		Note 3
Response Time		T_{ON}	25℃	-	30	-	ms	Note 4
		T_{OFF}						
Chromaticity	White	x	Backlight is on	0.278	0.298	0.318		Note 1,5
		y		0.294	0.314	0.334		
	Red	x						Note 1,5
		y						
	Green	x						Note 1,5
		y						
	Blue	x						Note 1,5
		y						
Uniformity		U		75	80	--	%	Note 6
Reflection ratio					7%			
Luminance		L		180	220	-	cd/m^2	Note 7

Test Conditions:

1. I_F= 20 mA, and the ambient temperature is 25℃.
2. The test systems refer to Note 1 and Note 2.

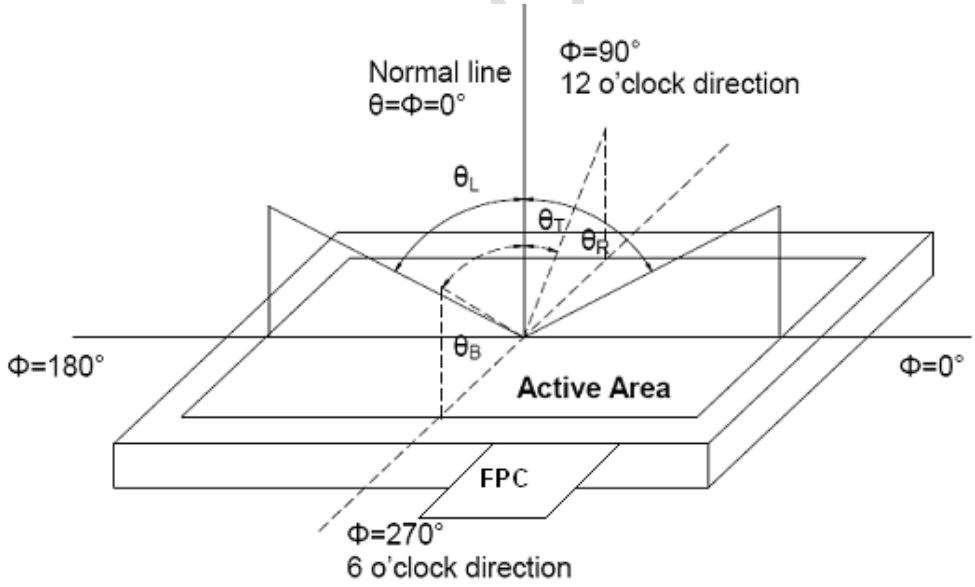
Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. After 5 Minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.



Note 2: Definition of viewing angle range and measurement system.

viewing angle is measured at the center point of the LCD.



Note 3: Definition of contrast ratio

$$\text{Contrast ratio (CR)} = \frac{\text{Luminance measured when LCD is on the "White" state}}{\text{Luminance measured when LCD is on the "Black" state}}$$

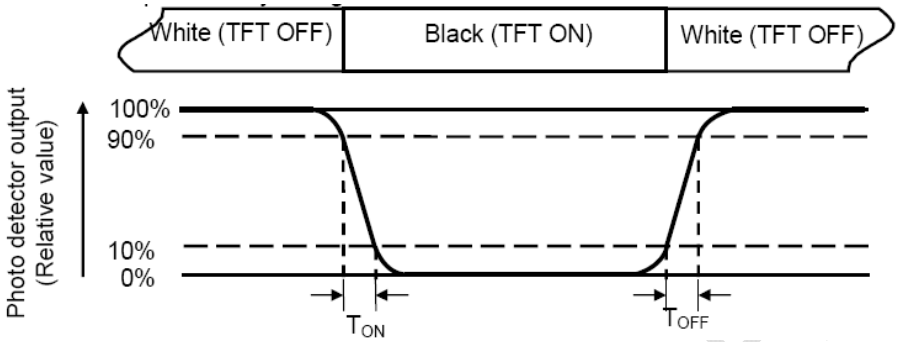
"White state ": The state is that the LCD should drive by Vwhite.

"Black state": The state is that the LCD should drive by Vblack.

Vwhite: To be determined Vblack: To be determined.

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between “White” state and “Black” state. Rise time (T_{ON}) is the time between photo detector output intensity changed from 90% to 10%. And fall time (T_{OFF}) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

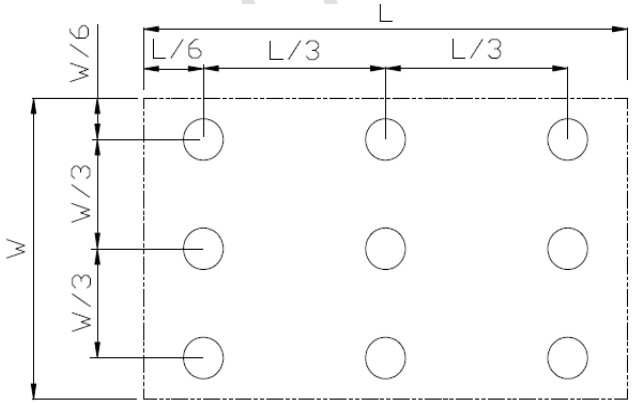
Color coordinates measured at center point of LCD.

Note 6: Definition of Luminance Uniformity

Active area is divided into 9 measuring areas (Refer Fig. 2). Every measuring point is placed at the center of each measuring area.

Luminance Uniformity (U) = Lmin/ Lmax

L-------Active area length W----- Active area width



Lmax: The measured Maximum luminance of all measurement position.

Lmin: The measured Minimum luminance of all measurement position.

Note 7: Definition of Luminance:

Measure the luminance of white state at center point.

7 Environmental / Reliability Test

No	Test Item	Condition	Remarks
1	High Temperature Operation	70℃, 120Hours	IEC60068-2-1:2007 GB2423.2-2008
2	Low Temperature Operation	-20℃, 120 Hours	IEC60068-2-1:2007 GB2423.1-2008
3	High Temperature Storage	80℃, 120 Hours	IEC60068-2-1:2007 GB2423.2-2008
4	Low Temperature Storage	-30℃, 120 Hours	IEC60068-2-1:2007 GB2423.1-2008
5	Storage at High Temperature and Humidity	50℃, 90%RH, 120 Hours	IEC60068-2-78 :2001 GB/T2423.3—2006
6	Thermal Shock (non-operation)	-10℃ , 30min.<=> 60℃ , 30min. 10 Cycles	Start with cold temperature, End with high temperature, IEC60068-2-14:1984,GB2423.22-2002
7	ESD	Voltage:±8KV R:330 ohm,C:150pF Air discharge,10 times	IEC61000-4-2:2001 GB/T17626.2-2006
8	Vibration Test	10 => 55 =>10 => 55 => 10 Hz, within 1 minute;Amplitude:1.5mm. 15 minutes for each Direction (X,Y,Z)	IEC60068-2-6:1982 GB/T2423.10—1995
10	Package Drop Test	Packed, 100CM free fall 6 sides, 1 corner, 3edges	IEC60068-2-32:1990 GB/T2423.8—1995

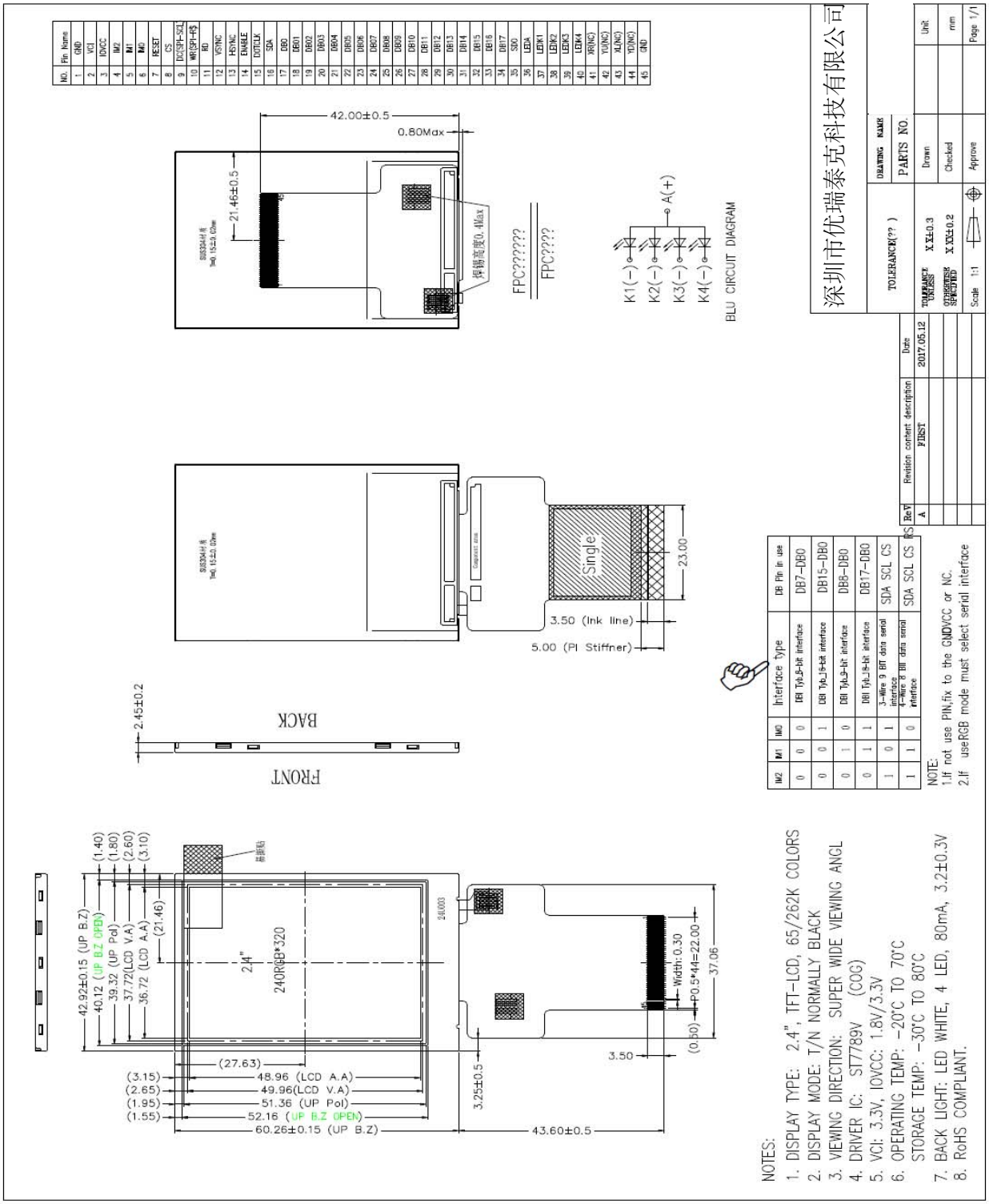
Note1: Ts is the temperature of panel's surface.

Note2: Ta is the ambient temperature of sample.

Note3: Before cosmetic and function test, the product must have enough recovery time, at least 2 hours at room temperature.

Note 4: In the standard condition, there shall be no practical problem that may affect the display function. After the reliability test, the product only guarantees operation, but don't guarantee all of the cosmetic specification.

8.Outline Dimension



9 Packing Drawing

TBD

10 Precautions for Use of LCD Modules

a) Handling Precautions

i. The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.

ii. If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.

iii. Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.

iv. The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.

v. If the display surface is contaMinated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:

- Isopropyl alcohol
- Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketone
- Aromatic solvents

vi. Do not attempt to disassemble the LCD Module.

vii. If the logic circuit power is off, do not apply the input signals.

viii. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

10.1.8.1 Be sure to ground the body when handling the LCD Modules.

10.1.8.2 Tools required for assembly, such as soldering irons, must be properly ground.

10.1.8.3 To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.

10.1.8.4 The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

b) Storage precautions

i. When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.

ii. The LCD modules should be stored under the storage temperature range. If the LCD modules will be stored for a long time, the recommend condition is:

Temperature : 0℃ ～ 40℃ Relatively humidity: ≤80%

iii. The LCD modules should be stored in the room without acid, alkali and harmful gas.

c) Transportation Precautions

i. The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.